

[54] **PINNED HEAT-SINK EXTRUSION FOR CIRCUIT-BOARD MOUNTING**

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[**] Term: **14 Years**

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[52] U.S. Cl. **D13/23**

[58] Field of Search **D13/23; 174/16 HS; 357/81; 165/80.1, 80.2, 80.3, 185; 361/386, 387, 388**

[56] **References Cited**

U.S. PATENT DOCUMENTS

3,303,392 2/1967 Zelina 361/388

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[57] **CLAIM**

The ornamental design for a pinned heat-sink extrusion for circuit-board mounting, substantially as shown.

DESCRIPTION

FIG. 1 is a perspective view of a pinned heat-sink extrusion for circuit-board mounting showing my new design;

FIG. 2 is a front elevational view thereof;

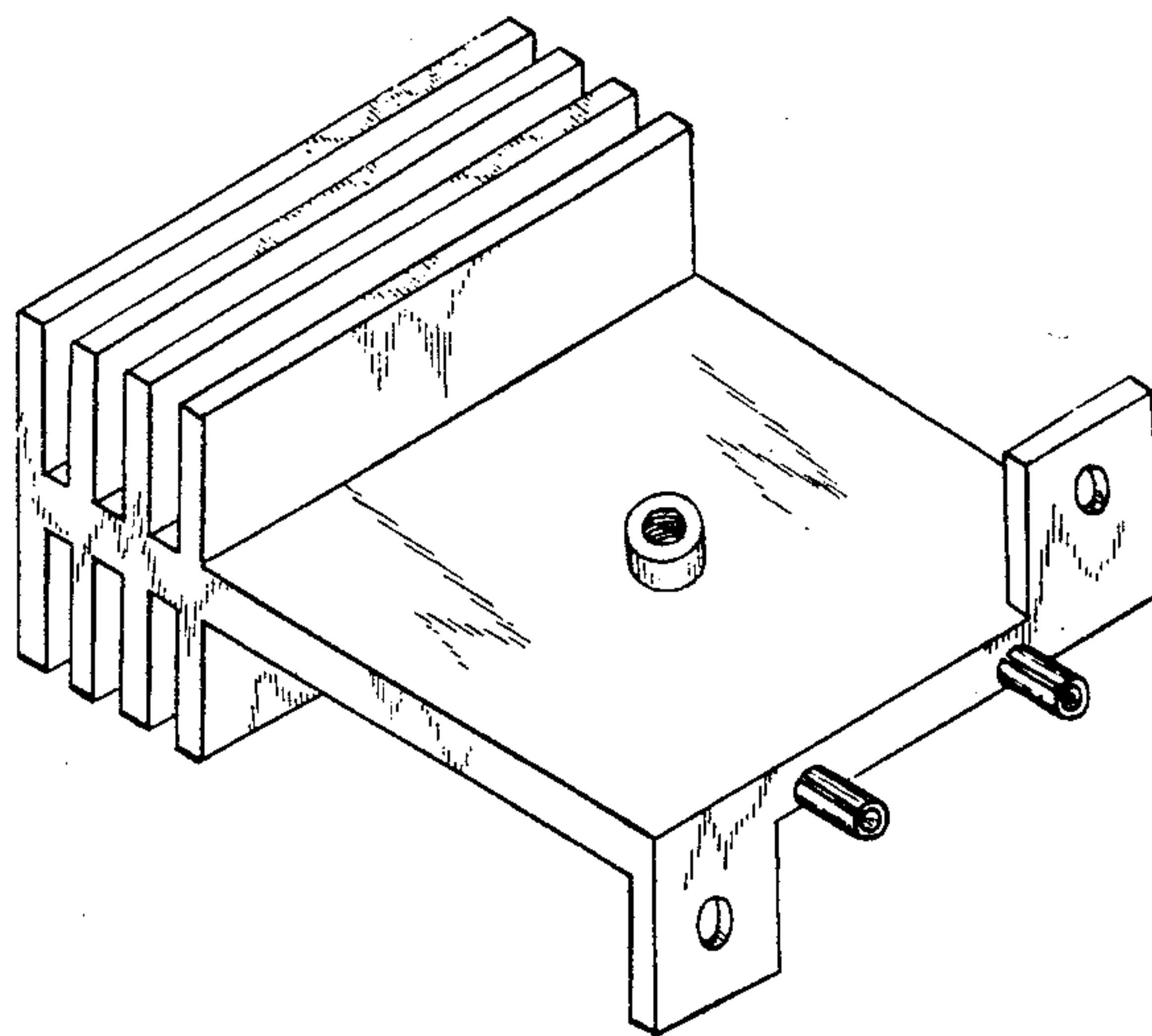
FIG. 3 is a top plan view thereof;

FIG. 4 is a bottom plan view thereof;

FIG. 5 is a rear elevational view thereof;

FIG. 6 is a side elevational view thereof, looking toward the right side thereof as it is shown in FIG. 1; and

FIG. 7 is a side elevational view thereof looking toward the left side thereof as it is shown in FIG. 1.



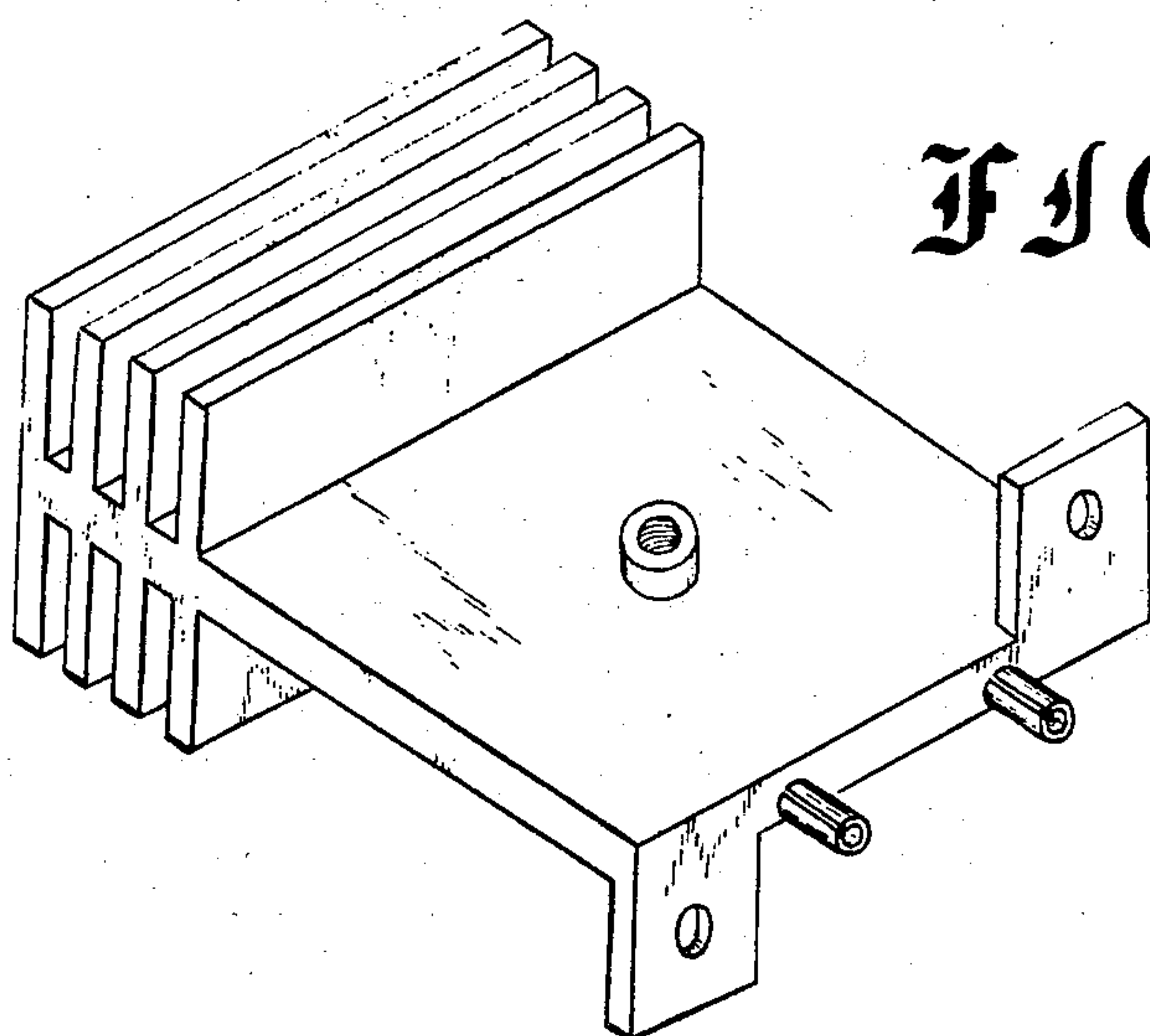


FIG. 1

FIG. 2

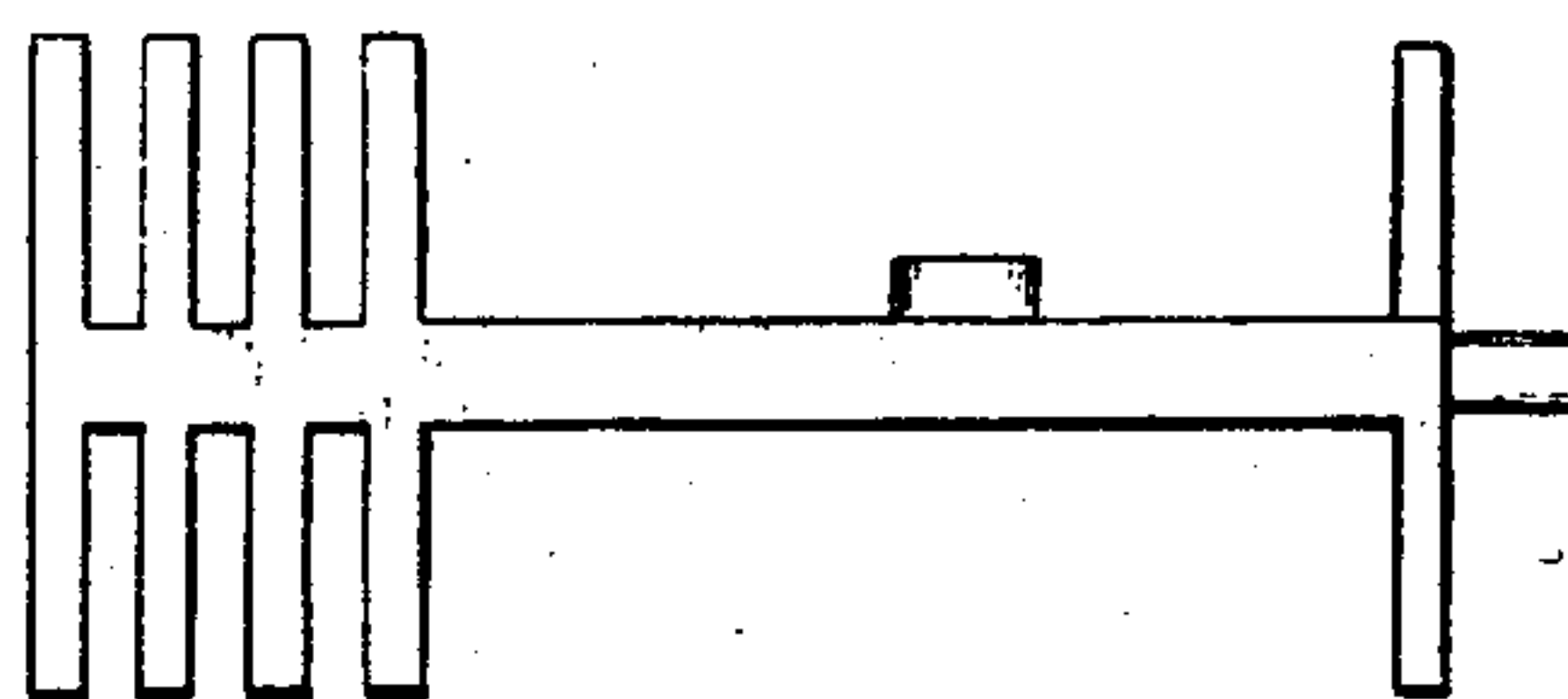


FIG. 3

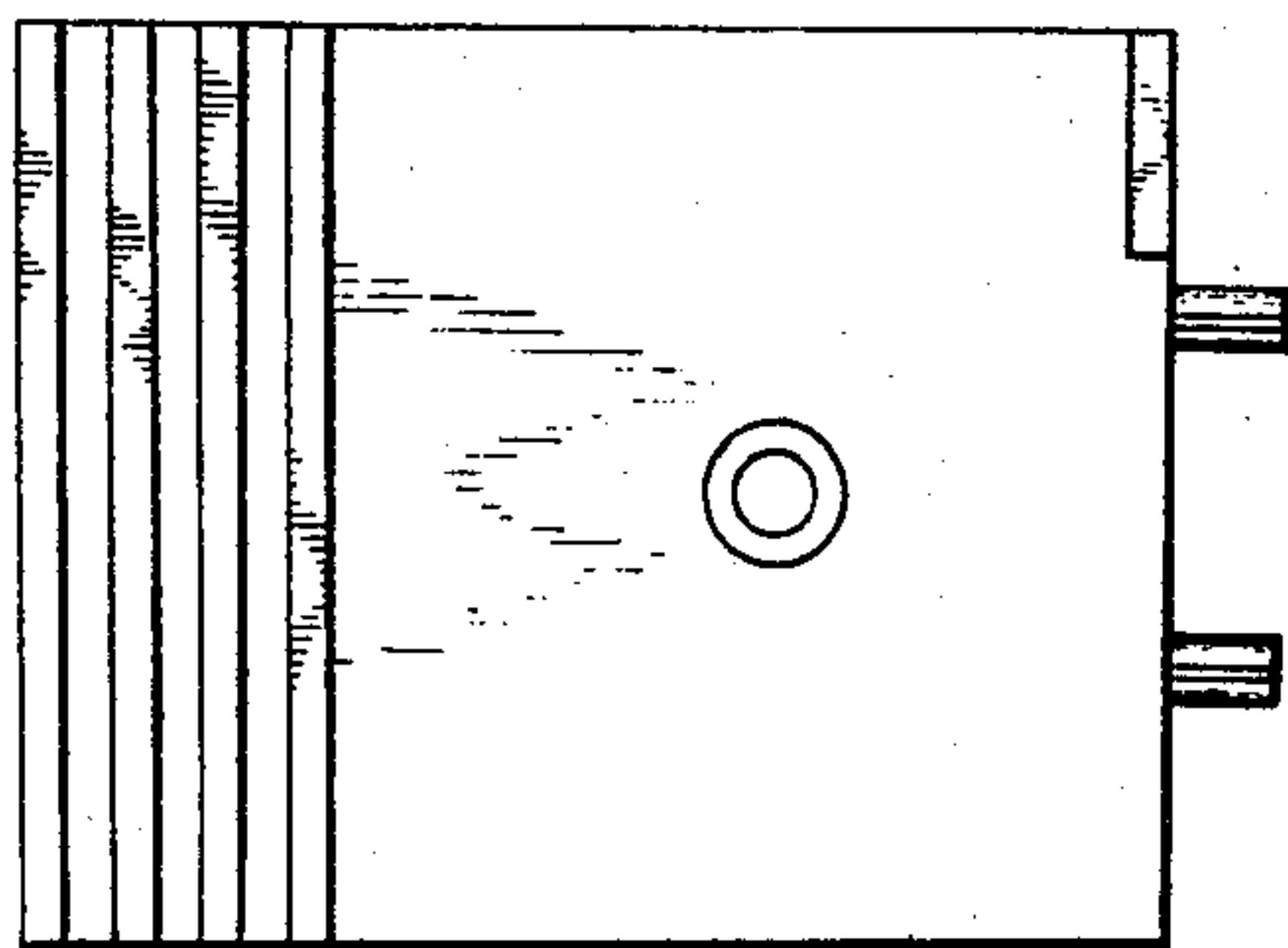


FIG. 5

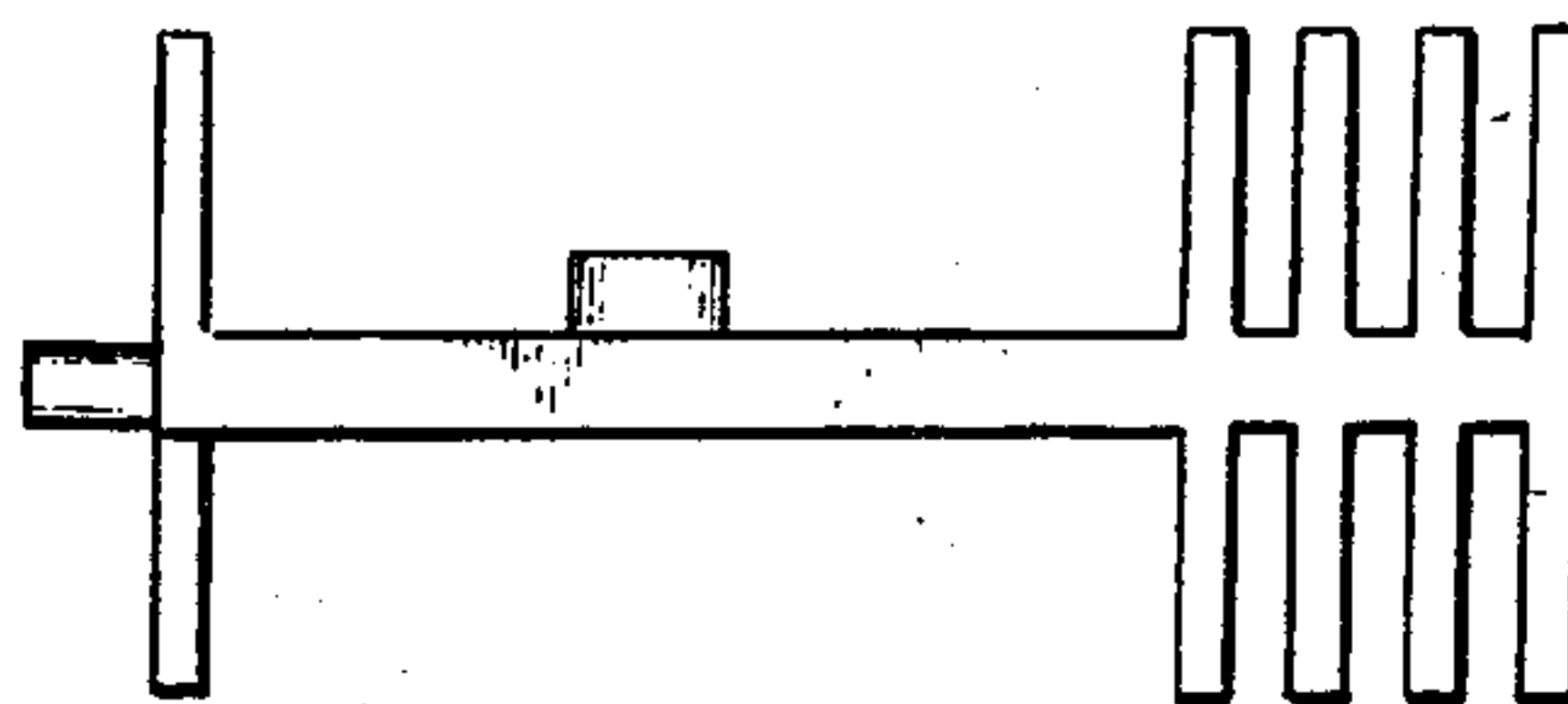


FIG. 4

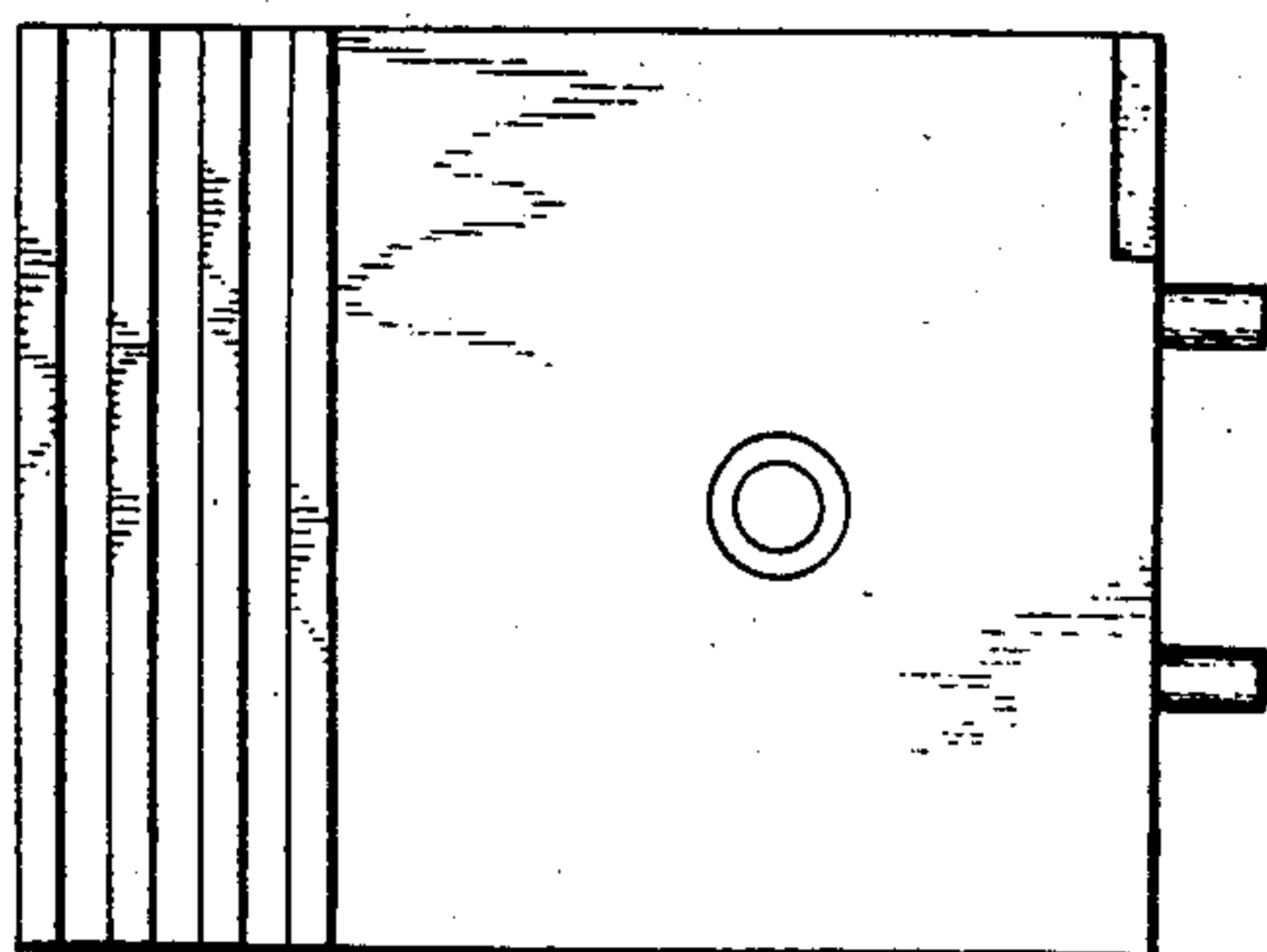


FIG. 6

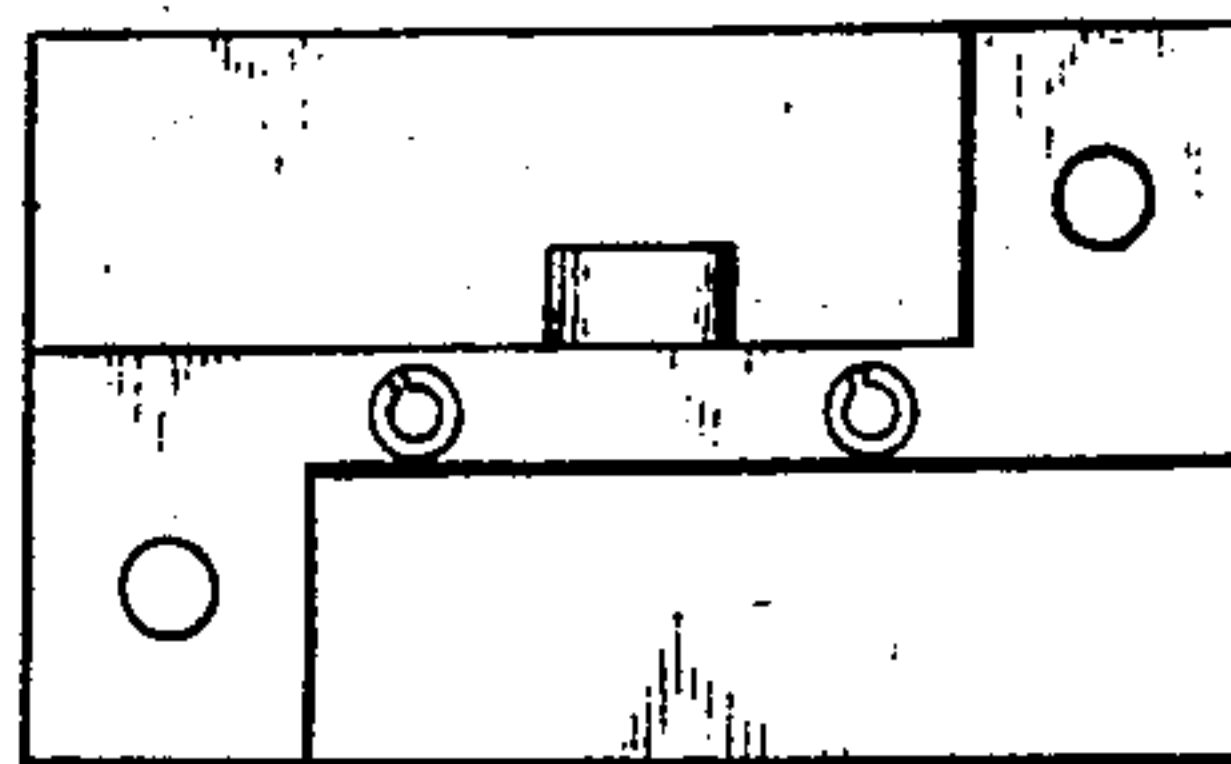


FIG. 7

